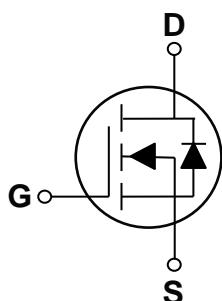
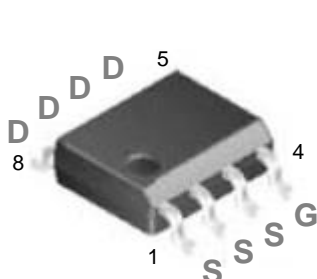


## 80V N-Channel MOSFETs

### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### SOP-8 Pin Configuration



BVDSS	RDSON	ID
80V	13mΩ	19A

### Features

- 80V, 19A,  $R_{DS(ON)} = 13m\Omega @ V_{GS} = 10V$
- Improved  $dv/dt$  capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Networking
- Load Switch
- LED applications

### Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	80	V
$V_{GS}$	Gate-Source Voltage	$\pm 25$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	19	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	12	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	48	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	180	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	60	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	10.2	W
	Power Dissipation – Derate above $25^\circ\text{C}$	0.82	W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-50 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-50 to 150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	12.2	$^\circ\text{C/W}$



# FTK8966A

## 80V N-Channel MOSFETs

Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	80	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1mA$	---	0.05	---	$V/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=80V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=64V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 25V, V_{DS}=0V$	---	---	$\pm 100$	nA

### On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=12A$	---	10.5	13	m $\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	2	3	4	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5	---	$mV/^\circ\text{C}$
$g_{fs}$	Forward Transconductance	$V_{DS}=10V, I_D=3A$	---	10	---	S

### Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$Q_g$	Total Gate Charge <sup>3,4</sup>	$V_{DS}=40V, V_{GS}=10V, I_D=10A$	---	31.2	48	nC
$Q_{gs}$	Gate-Source Charge <sup>3,4</sup>		---	9	18	
$Q_{gd}$	Gate-Drain Charge <sup>3,4</sup>		---	9.2	18	
$T_{d(on)}$	Turn-On Delay Time <sup>3,4</sup>	$V_{DD}=40V, V_{GS}=10V, R_G=6\Omega, I_D=1A$	---	22	44	ns
$T_r$	Rise Time <sup>3,4</sup>		---	16	32	
$T_{d(off)}$	Turn-Off Delay Time <sup>3,4</sup>		---	40	80	
$T_f$	Fall Time <sup>3,4</sup>		---	31	62	
$C_{iss}$	Input Capacitance	$V_{DS}=30V, V_{GS}=0V, F=1MHz$	---	1810	2700	pF
$C_{oss}$	Output Capacitance		---	252	380	
$C_{rss}$	Reverse Transfer Capacitance		---	100	150	
$R_g$	Gate resistance	$V_{GS}=0V, V_{DS}=0V, F=1MHz$	---	1.45	2.9	$\Omega$

### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	19	A
$I_{SM}$	Pulsed Source Current		---	---	38	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=60A$ ., Starting  $T_J=25^\circ\text{C}$
3. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

## 80V N-Channel MOSFETs

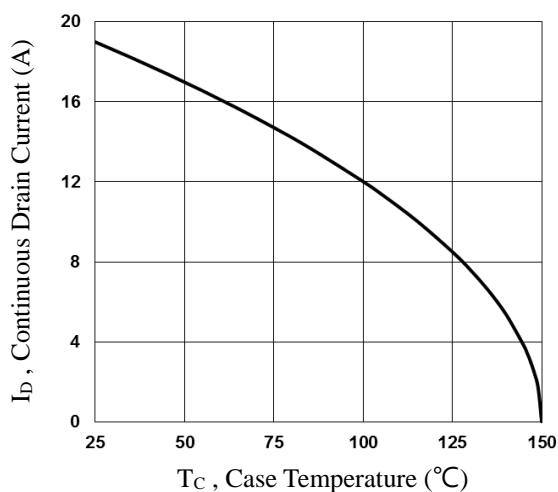


Fig.1 Continuous Drain Current vs.  $T_c$

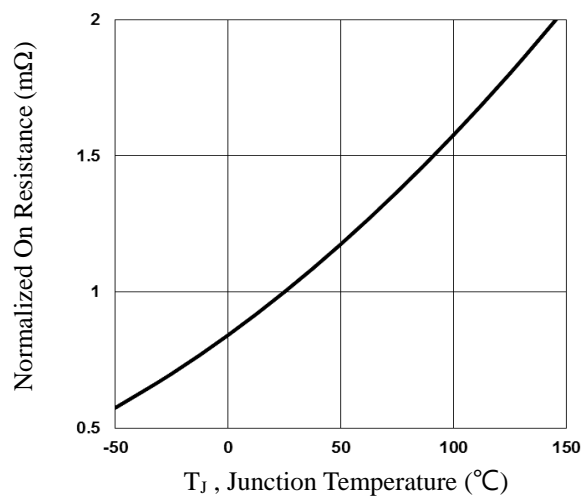


Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$

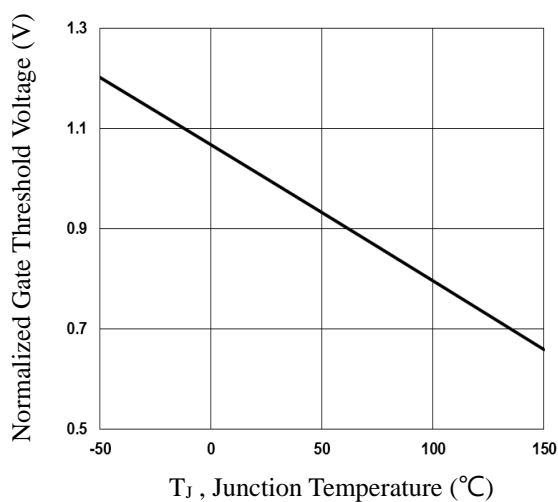


Fig.3 Normalized  $V_{th}$  vs.  $T_J$

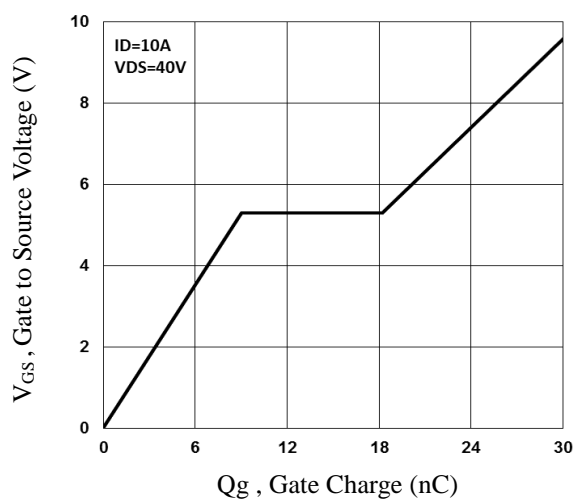


Fig.4 Gate Charge Characteristics

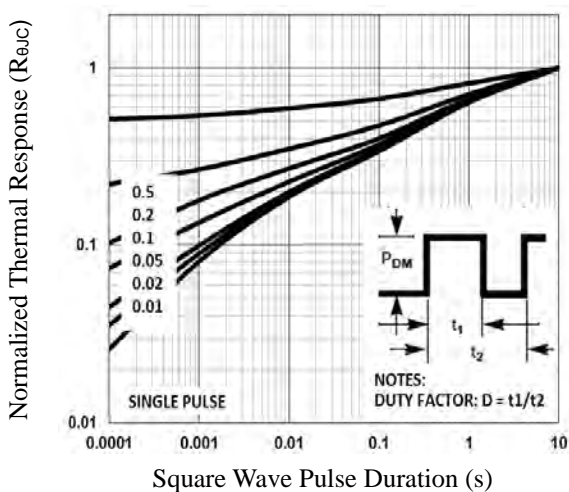


Fig.5 Normalized Transient Impedance

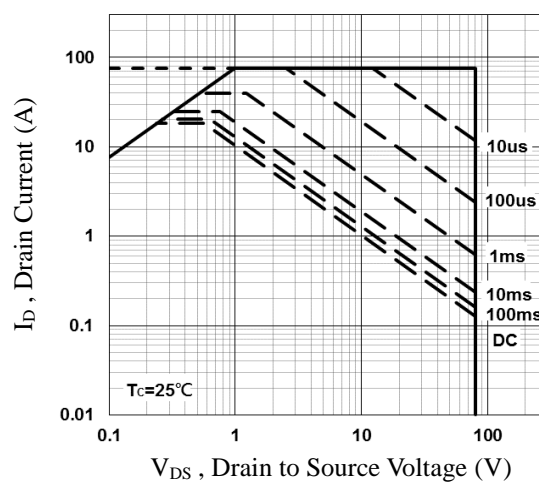


Fig.6 Maximum Safe Operation Area

## 80V N-Channel MOSFETs

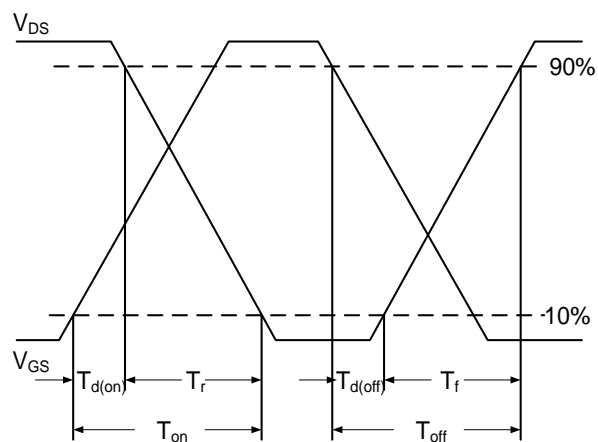


Fig.7 Switching Time Waveform

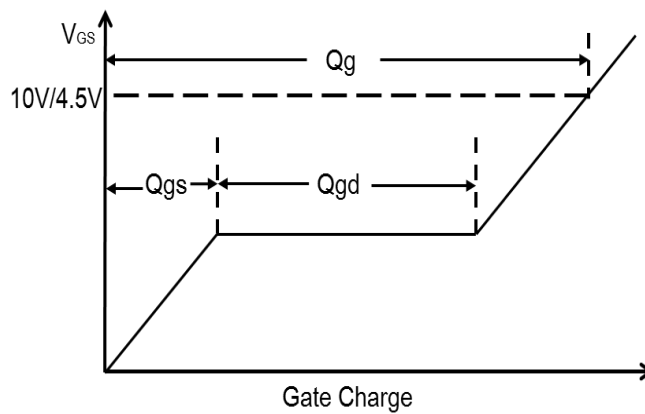
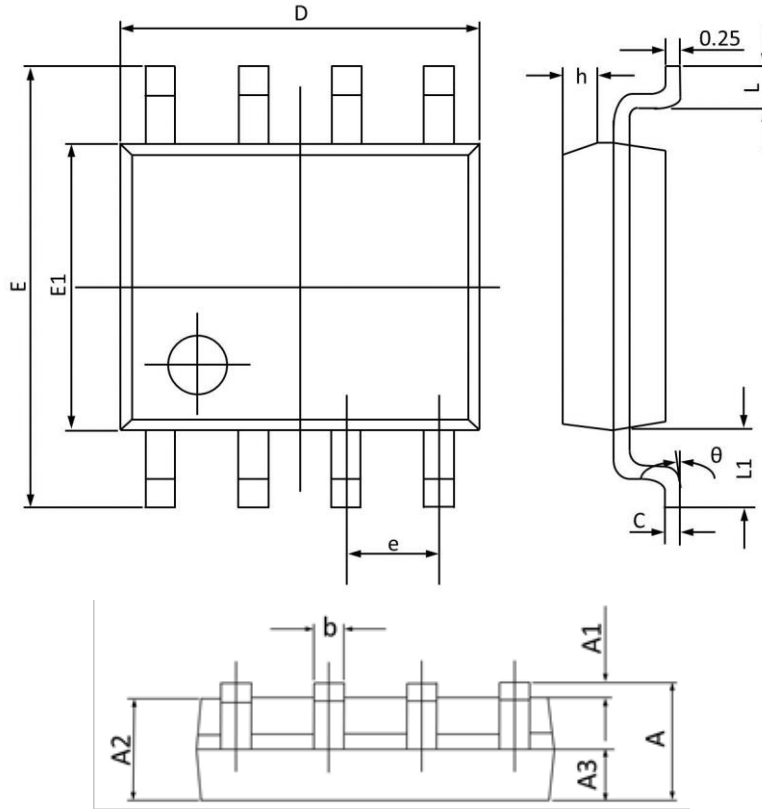


Fig.8 Gate Charge Waveform

## 80V N-Channel MOSFETs

### SOP-8 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.068
A1	0.100	0.250	0.004	0.009
A2	1.300	1.500	0.052	0.059
A3	0.600	0.700	0.024	0.027
b	0.390	0.480	0.016	0.018
c	0.210	0.260	0.009	0.010
D	4.700	5.100	0.186	0.200
E	5.800	6.200	0.229	0.244
E1	3.700	4.100	0.146	0.161
e	1.270(BSC)		0.050(BSC)	
h	0.250	0.500	0.010	0.019
L	0.500	0.800	0.019	0.031
L1	1.050(BSC)		0.041(BSC)	
theta	0°	8°	0°	8°